

## 2A DDR Termination Regulator

### FEATURES

- Source and sink current capability of 2A
- Low output voltage offset,  $\pm 20\text{mV}$
- High accuracy output voltage at full-load
- $V_{\text{OUT}}$  adjustable by external resistors
- Low external component count
- Current limit protection
- Thermal protection
- SO-8 and TO-252-5 packages

### APPLICATIONS

- Mother Boards
- Graphic Cards
- DDR Termination Voltage Supply - supports
  - DDR1 (1.25V<sub>TT</sub>), DDR2 (0.9V<sub>TT</sub>), and meets
  - JEDEC SSTL-2 and SSTL-3 term. specifications

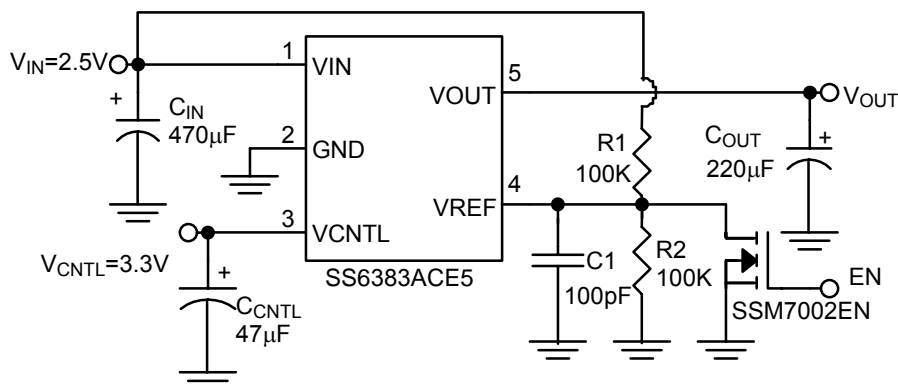
### DESCRIPTION

The SS6383A linear regulator is designed to provide 2A source and sink current while regulating an output voltage to within 20mV.

The SS6383A converts voltage supplies ranging from 1.6V to 6V into an output voltage that is set by two external voltage-divider resistors. It provides an excellent voltage source for active termination schemes for high-speed transmission lines such as those seen in high-speed memory buses.

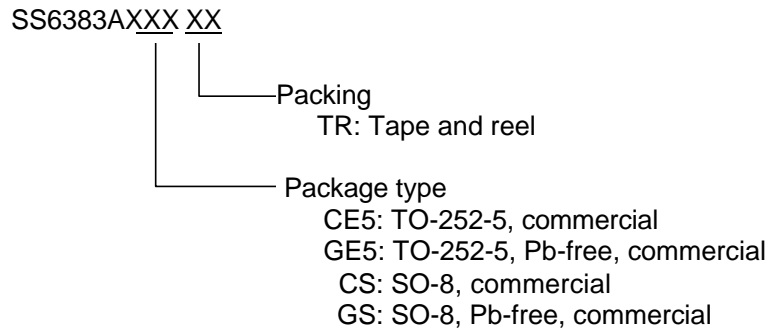
The built-in current-limiting in source and sink mode, together with thermal shutdown, provides maximum protection to the SS6383A against fault conditions.

### TYPICAL APPLICATION CIRCUIT



 This device is available with Pb-free lead finish (second-level interconnect) as SS6383AGxx

## ORDERING INFORMATION



Example:       SS6383AGE5TR  
           → in TO-252-5 package, Pb-free lead finish,  
               shipped on tape and reel

## PIN CONFIGURATION

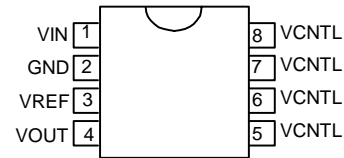
### TO-252-5

TOP VIEW  
 1: VIN  
 2: GND  
 3: VCNTL  
 4: VREF  
 5: VOUT



### SO-8

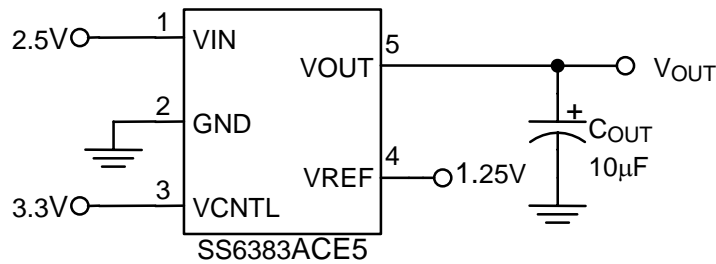
TOP VIEW



## ABSOLUTE MAXIMUM RATINGS

Supply Voltage.....		-0.4V to 7V
Operating Temperature Range.....		-40°C~85°C
Storage Temperature Range.....		-65°C ~150°C
Lead Temperature (Solder, 10sec).....		260°C
Thermal Resistance $\theta_{JC}$	TO-252.....	12.5°C /W
	SO-8 .....	40°C /W
Thermal Resistance $\theta_{JA}$	TO-252.....	100°C /W
(Assumes no ambient airflow, no heatsink)	SO-8.....	160°C /W

**Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.**

**TEST CIRCUIT**

**ELECTRICAL CHARACTERISTICS**

( $V_{CNTL}=3.3V$ ,  $V_{IN}=2.5V$ ,  $V_{REF}=0.5V_{IN}$ ,  $C_{OUT}=10\mu F$ ,  $T_A=25^\circ C$ , unless otherwise specified)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Input Voltage (DDR1/2)	Keep $V_{CNTL} \geq V_{IN}$ during power on and off sequences	$V_{IN}$	1.6	2.5/1.8		V
		$V_{CNTL}$	3.0	3.3	6	
Output Voltage	$I_{OUT} = 0mA$	$V_{OUT}$		$V_{REF}$		V
Output Voltage Offset	$I_{OUT} = 0mA$	$V_{OS}$	-20		20	mV
Load Regulation (DDR1/2)	$I_{OUT} = 0.1mA \sim +2A$	$\Delta V_{LOR}$		10	20	mV
	$I_{OUT} = 0.1mA \sim -2A$			10	20	
Quiescent Current	$V_{REF} < 0.2V$ , $V_{OUT} = OFF$	$I_Q$		8	30	$\mu A$
Operating Current of $V_{CNTL}$	No load	$I_{CNTL}$		3	10	mA
$V_{REF}$ Bias Current	$V_{REF} = 1.25V$		0		1	$\mu A$
Current Limit		$I_{IL}$	2.2	3	4.5	A
<b>THERMAL PROTECTION</b>						
Thermal Shutdown Temperature	$3.3V \leq V_{CNTL} \leq 5V$	$T_{SD}$	125	150		$^\circ C$
Thermal Shutdown Hysteresis	Guaranteed by design			30		$^\circ C$
<b>SHUTDOWN SPECIFICATIONS</b>						
Shutdown Threshold	Output ON ( $V_{REF} = 0V \rightarrow 1.25V$ )		0.8			V
	Output OFF ( $V_{REF} = 1.25V \rightarrow 0V$ )				0.2	

Note 2:  $V_{OS}$  is the voltage measurement, which is defined as the difference between  $V_{OUT}$  and  $V_{REF}$ .

Note 3: Load regulation is measured at constant junction temperature, using pulse testing with a low ON time.

Note 4: Current limit is measured by pulsing a short time.

Note 5: To operate the system safely;  $V_{CNTL}$  must be always greater than  $V_{IN}$ .

Note 6: Specifications are guaranteed by Statistical Quality Controls (SQC), and not production tested, within the operating temperature range of  $-40^\circ C$  to  $85^\circ C$ .

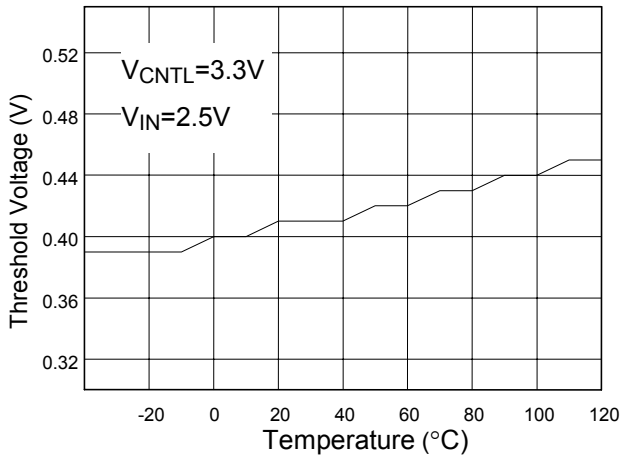
**TYPICAL PERFORMANCE CHARACTERISTICS**


Fig. 1 Turn-On Threshold vs. Temp.

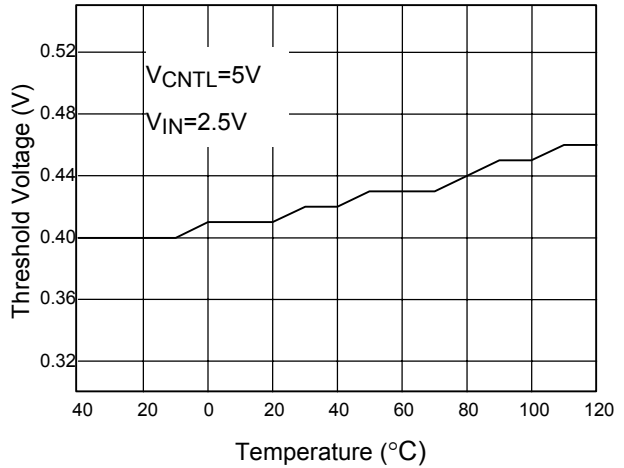


Fig. 2 Turn On Threshold vs. Temp.

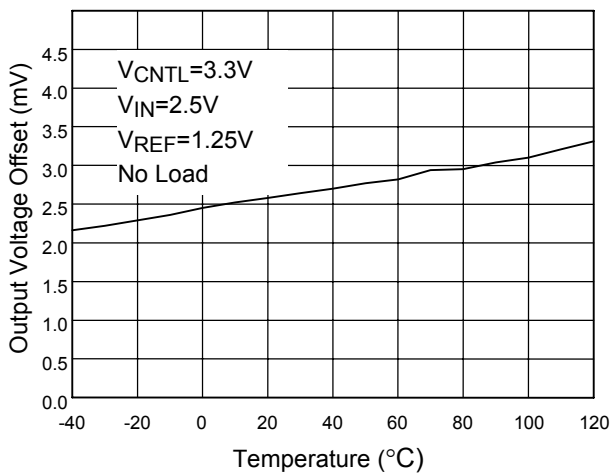


Fig. 3 Output Voltage Offset vs. Temp.

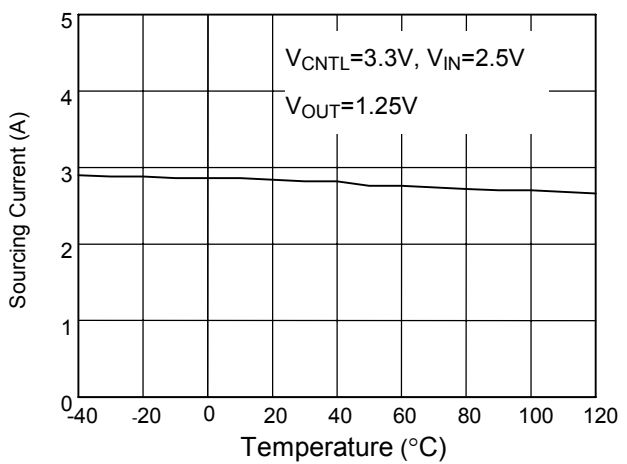


Fig. 4 Current-Limit (Sourcing) vs. Temp.

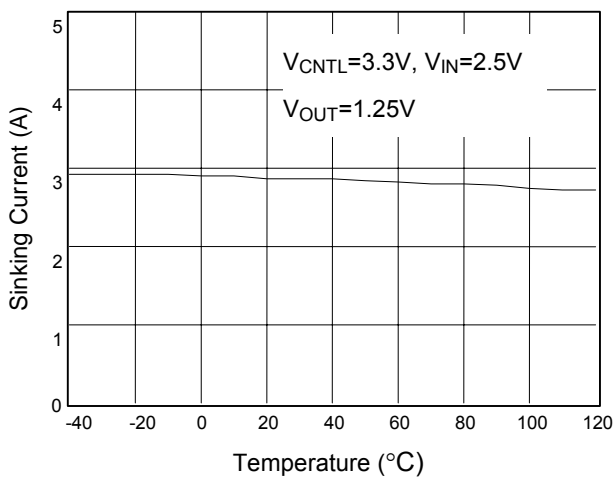


Fig. 5 Current Limit (Sinking) vs. Temp.

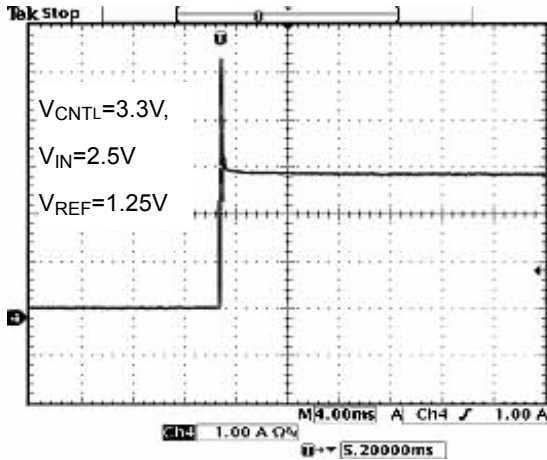
**TYPICAL PERFORMANCE CHARACTERISTICS (Continued)**


Fig. 6 Output Short-Circuit (Sinking)

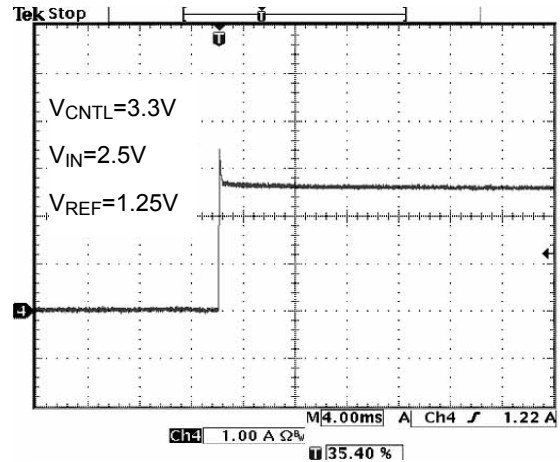
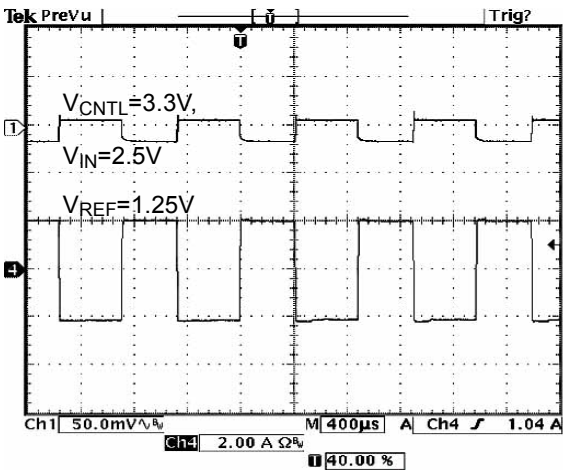
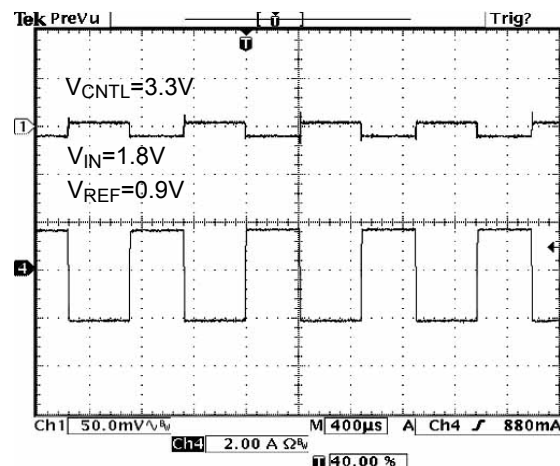
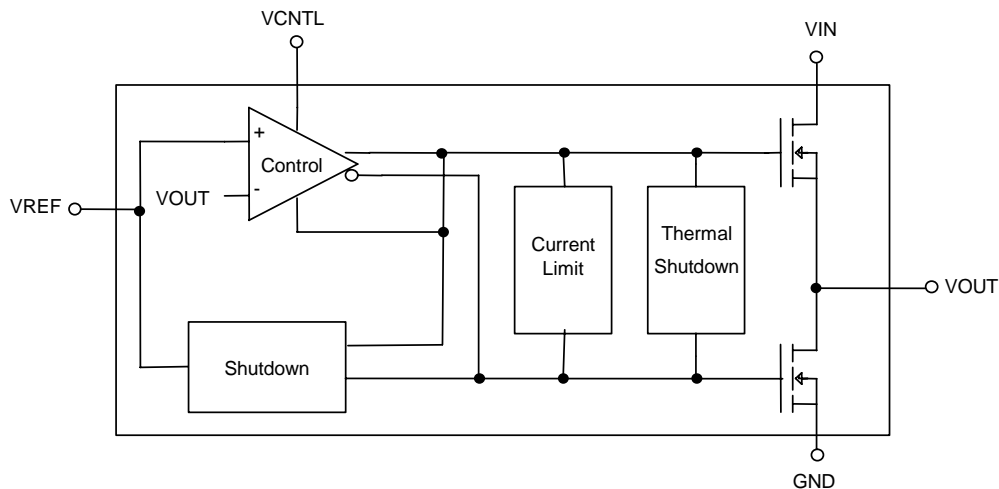


Fig. 7 Output Short-Circuit (Sourcing)


 Fig. 8 Transient Response at 1.25V<sub>TT</sub>/2A

 Fig. 9 Transient Response at 0.9V<sub>TT</sub>/2A

**BLOCK DIAGRAM**


## PIN DESCRIPTIONS (TO-252-5)

- PIN 1: VIN - Input supply pin. It provides main power to create the external reference voltage by divider resistors for regulating VREF and VOUT.
- PIN 2: GND - Ground pin.
- PIN 3: VCNTL - Input supply pin. It is used to supply all the internal control circuitry.

- PIN 4: VREF - Reference voltage input. Pull this pin low to shutdown device.
- PIN 5: VOUT - Output pin.

## APPLICATION INFORMATION

### Layout Consideration

As the SS6383A is in SO-8 and TO-252-5 packages, it is unable to dissipate heat easily when it operates at high current. To avoid exceeding the maximum junction temperature, a suitable copper area must be used.

The large copper area shown at V<sub>CNTL</sub> pins is able to relieve the thermal dissipation. Using the via to direct heat into the large copper area shown on the bottom layer also helps significantly. All capacitors should be placed as close as possible to the relevant pins.

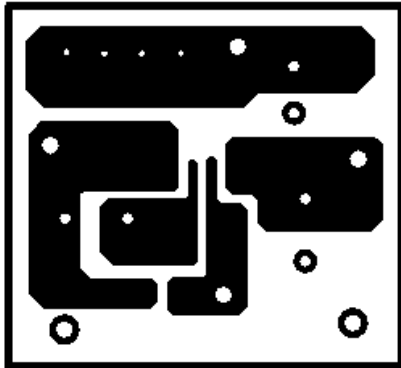


Figure 10. Top layer

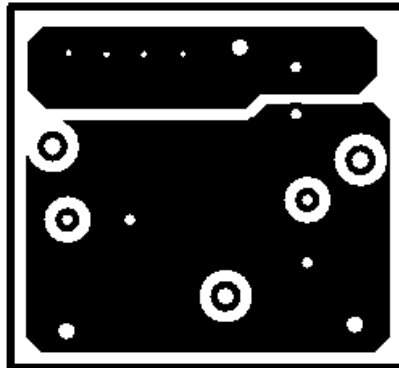


Figure 11. Bottom layer

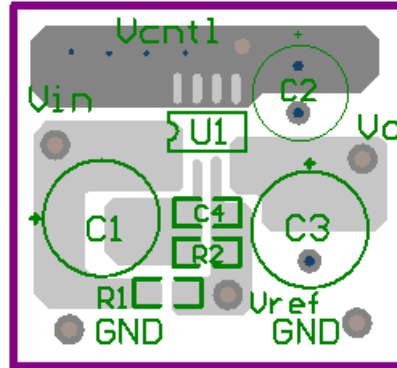
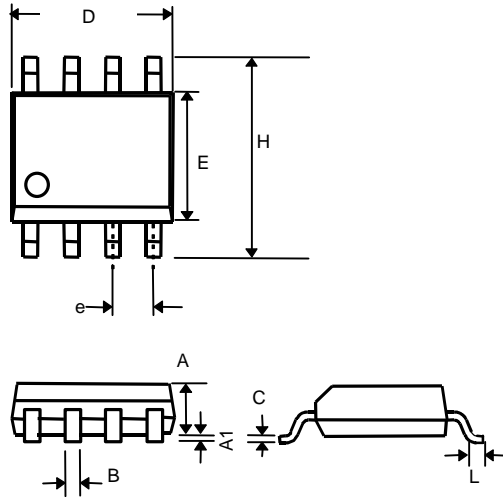
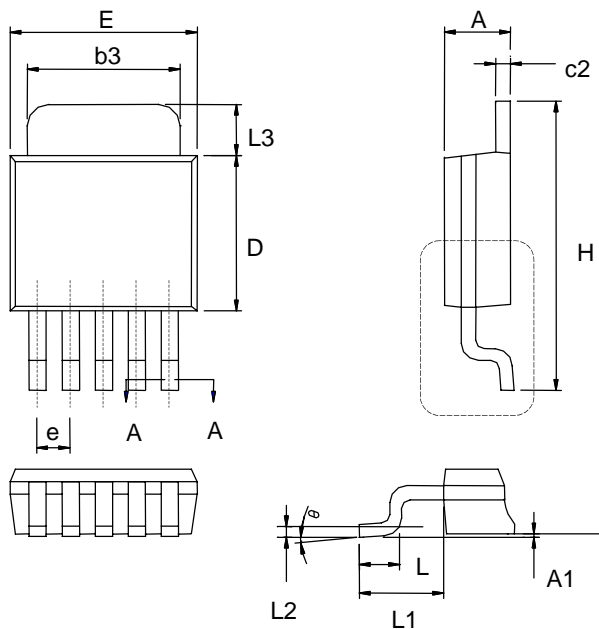


Figure 12. Placement

**PHYSICAL DIMENSIONS**
**SO-8**


SYMBOL	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27(TYP)	
H	5.80	6.20
L	0.40	1.27

**TO-252-5**


SYMBOL	MIN	MAX
A	2.19	2.38
A1	0	0.13
b3	5.21	5.46
c2	0.46	0.58
D	5.33	5.59
E	6.35	6.73
e	1.27 BSC	
H	9.40	10.41
L	1.4	1.78
L1	2.67 REF	
L2	0.51 BSC	
L3	1.52	2.03
$\theta$	0°	8°

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